Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTION:**

1. **GND**

**.013”**

**ANODE**

**.006 x .006”**

**.013”**

**Top Material: Al**

**Backside Material: Aui**

**Bond Pad Size: .006 x .006”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .013” X .013” DATE: 8/31/21**

**MFG: MOTOROLA THICKNESS .006” P/N: 1N914**

**DG 10.1.2**

#### Rev B, 7/1